

Abstract

An object of the present invention is to provide an electronic part device which can be repaired even in the case of an electronic part device having a malfunction in electrical connection after carrying out underfill.

The present invention is an electronic part device in which a semiconductor element (flip chip) (3) is mounted on a wiring circuit substrate (1) under such a state that an electrode part for connection (joint ball) disposed on the semiconductor element (flip chip) (3) and a circuit electrode (5) disposed on the wiring circuit substrate (1) are facing with each other. In addition, the gap between the wiring circuit substrate (1) and the semiconductor element (flip chip) (3) is filled by a filling resin layer (4) comprising a liquid epoxy resin composition which comprises the following component (D) and the following components (A) to (C).

- (A) A liquid epoxy resin.
- (B) A curing agent.
- (C) An N,N,N',N'-tetra-substituted fluorine-containing aromatic diamine compound.
- (D) A carboxylic acid vinyl ether addition product.